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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	<u> </u>
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc54c-04-ss

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

5.0 RESET

PIC16C5X devices may be RESET in one of the following ways:

- Power-On Reset (POR)
- MCLR Reset (normal operation)
- MCLR Wake-up Reset (from SLEEP)
- WDT Reset (normal operation)
- WDT Wake-up Reset (from SLEEP)

Table 5-1 shows these RESET conditions for the PCL and STATUS registers.

Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-On Reset (POR), MCLR or WDT Reset. A MCLR or WDT wake-up from SLEEP also results in a device RESET, and not a continuation of operation before SLEEP. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits (STATUS <4:3>) are set or cleared depending on the different RESET conditions (Table 5-1). These bits may be used to determine the nature of the RESET.

Table 5-3 lists a full description of RESET states of all registers. Figure 5-1 shows a simplified block diagram of the On-chip Reset circuit.

TABLE 5-1: STATUS BITS AND THEIR SIGNIFICANCE

Condition	ТО	PD
Power-On Reset	1	1
MCLR Reset (normal operation)	u	u
MCLR Wake-up (from SLEEP)	1	0
WDT Reset (normal operation)	0	1
WDT Wake-up (from SLEEP)	0	0

Legend: u = unchanged, x = unknown, - = unimplemented read as '0'.

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH RESET

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	<u>Value</u> on MCLR and WDT Reset
03h	STATUS	PA2	PA1	PA0	TO	PD	Z	DC	С	0001 1xxx	000q quuu

Legend: u = unchanged, x = unknown, q = see Table 5-1 for possible values.

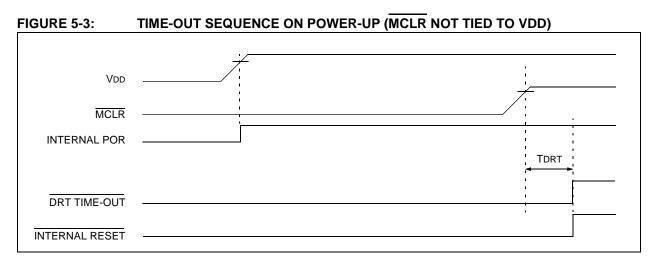


FIGURE 5-4: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): FAST VDD RISE TIME

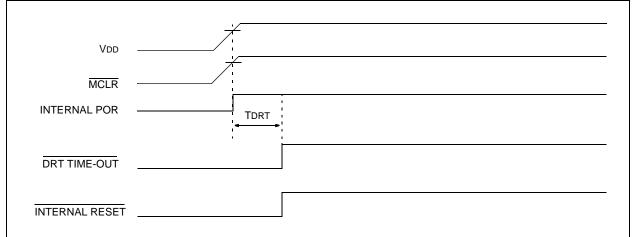
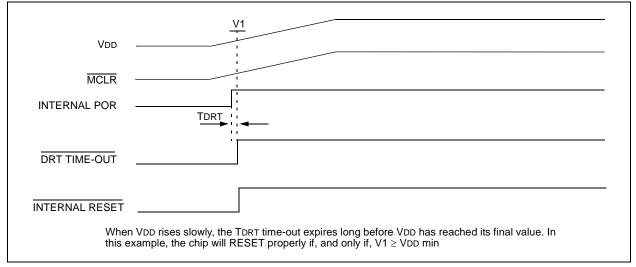


FIGURE 5-5: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): SLOW VDD RISE TIME







9.2 Watchdog Timer (WDT)

The Watchdog Timer (WDT) is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins have been stopped, for example, by execution of a SLEEP instruction. During normal operation or SLEEP, a WDT Reset or Wake-up Reset generates a device RESET.

The $\overline{\text{TO}}$ bit (STATUS<4>) will be cleared upon a Watchdog Timer Reset (Section 6.3).

The WDT can be permanently disabled by programming the configuration bit WDTE as a '0' (Section 9.1). Refer to the PIC16C5X Programming Specifications (Literature Number DS30190) to determine how to access the configuration word.

9.2.1 WDT PERIOD

An 8-bit counter is available as a prescaler for the Timer0 module (Section 8.2), or as a postscaler for the Watchdog Timer (WDT), respectively. For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the WDT, but not

both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine prescaler assignment and prescale ratio (Section 6.4).

The WDT has a nominal time-out period of 18 ms (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the OPTION register. Thus, time-out a period of a nominal 2.3 seconds can be realized. These periods vary with temperature, VDD and part-to-part process variations (see Device Characterization).

Under worst case conditions (VDD = Min., Temperature = Max., WDT prescaler = 1:128), it may take several seconds before a WDT time-out occurs.

9.2.2 WDT PROGRAMMING CONSIDERATIONS

The CLRWDT instruction clears the WDT and the prescaler, if assigned to the WDT, and prevents it from timing out and generating a device RESET.

The SLEEP instruction RESETS the WDT and the prescaler, if assigned to the WDT. This gives the maximum SLEEP time before a WDT Wake-up Reset.

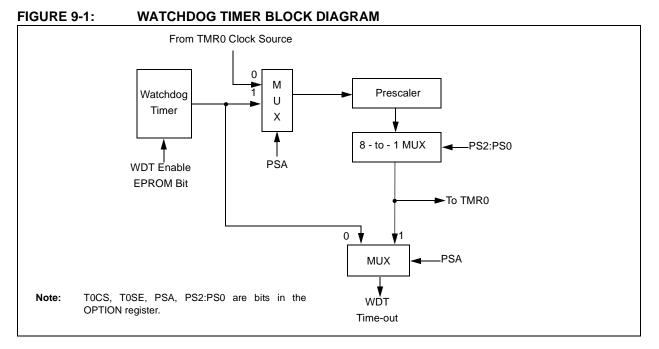


TABLE 9-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	<u>Value</u> on MCLR and WDT Reset
N/A	OPTION	—		Tosc	Tose	PSA	PS2	PS1	PS0	11 1111	11 1111

Legend: u = unchanged, - = unimplemented, read as '0'. Shaded cells not used by Watchdog Timer.

BSF Bit Set f								
Syntax:	[label]	[label] BSF f,b						
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$							
Operation:	$1 \rightarrow (f < b >)$							
Status Affected:	None							
Encoding:	0101	bbbf	ffff					
Description:	Bit 'b' in register 'f' is set.							
Words:	1							
Cycles:	1							
Example:	BSF	FLAG_RE	G, 7					
Before Instruction FLAG_REG = 0x0A After Instruction								
FLAG_F	REG = 0	IXOA						

BTFSC	Bit Test f, Skip if Clear								
Syntax:	[label] BTFSC f,b								
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$								
Operation:	skip if $(f < b >) = 0$								
Status Affected:	None								
Encoding:	0110 bbbf ffff								
Description:	If bit 'b' in register 'f' is 0 then the next instruction is skipped. If bit 'b' is 0 then the next instruc- tion fetched during the current instruction execution is discarded, and a NOP is executed instead, making this a 2-cycle instruction.								
Words:	1								
Cycles:	1(2)								
Example:	HERE BTFSC FLAG,1 FALSE GOTO PROCESS_CODE TRUE • •								
Before Instru	uction								
PC After Instruct if FLAG PC if FLAG PC	<pre><1> = 0, = address (TRUE);</pre>								

BTFSS	Bit Test f, Skip if Set								
Syntax:	[label]	BTFSS f	,b						
Operands:	$0 \leq f \leq 31$								
	0 ≤ b < 7								
Operation:	skip if (f<	:b>) = 1							
Status Affected:	None								
Encoding:	0111	bbbf	ffff						
Description:	If bit 'b' in register 'f' is '1' then the next instruction is skipped. If bit 'b' is '1', then the next instruc- tion fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a 2-cycle instruction.								
Words:	1								
Cycles:	1(2)								
Example:	BTFSS GOTO •	FLAG,1 PROCESS_C	ODE						
Before Inst	ruction								
PC After Instru	=	addres	SS (HERE)						
After Instru If FLAG PC if FLAG	<1> =	0, addres 1,	SS (FALSE);						
PC	SS (TRUE)								

RLF	Rotate Left f through Carry									
Syntax:	[<i>label</i>] RLF f,d									
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$									
Operation:	See description below									
Status Affected:	С									
Encoding:	0011 01df ffff									
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag (STATUS<0>). If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'									
Words:	1									
Cycles:	1									
Example:	RLF REG1,0									
Before Instru REG1 C After Instruct	= 1110 0110 = 0 tion									
REG1 W C	= 1110 0110 = 1100 1100 = 1									

RRF	Rotate Right f through Carry									
Syntax:	[<i>label</i>] RRF f,d									
Operands:	$\begin{array}{l} 0\leq f\leq 31\\ d\in [0,1] \end{array}$									
Operation:	See description below									
Status Affected:	С									
Encoding:	0011 00df ffff									
Description:	The contents of register 'f' are rotated one bit to the right through the Carry Flag (STATUS<0>). If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.									
Words:	1									
Cycles:	1									
Example:	RRF REG1,0									
Before Instru REG1 C After Instruct	$= 1110 0110 \\ = 0$									
REG1 W C	= 1110 0110 = 0111 0011 = 0									

SLEEP	Enter SLEEP Mode							
Syntax:	[<i>label</i>] SLEEP							
Operands:	None							
Operation:	00h \rightarrow WDT; 0 \rightarrow WDT prescaler; if assigned 1 \rightarrow TO; 0 \rightarrow PD							
Status Affected:	TO, PD							
Encoding:	0000 0000 0011							
Description:	Time-out status bit (\overline{TO}) is set. The power-down status bit (\overline{PD}) is cleared. The WDT and its pres- caler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See section on SLEEP for more details.							
Words:	1							
Cycles:	1							
Example:	SLEEP							

11.13 PICDEM 3 Low Cost PIC16CXXX Demonstration Board

The PICDEM 3 demonstration board is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with an LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 3 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer with an adapter socket, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 3 demonstration board to test firmware. A prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM 3 demonstration board is a LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM 3 demonstration board provides an additional RS-232 interface and Windows software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

11.14 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. All necessary hardware is included to run basic demo programs, which are supplied on a 3.5-inch disk. A programmed sample is included and the user may erase it and program it with the other sample programs using the PRO MATE II device programmer, or the PICSTART Plus development programmer, and easily debug and test the sample code. In addition, the PICDEM 17 demonstration board supports downloading of programs to and executing out of external FLASH memory on board. The PICDEM 17 demonstration board is also usable with the MPLAB ICE in-circuit emulator, or the PICMASTER emulator and all of the sample programs can be run and modified using either emulator. Additionally, a generous prototype area is available for user hardware.

11.15 KEELOQ Evaluation and Programming Tools

KEELOQ evaluation and programming tools support Microchip's HCS Secure Data Products. The HCS evaluation kit includes a LCD display to show changing codes, a decoder to decode transmissions and a programming interface to program test transmitters.

12.3 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

PIC16C (Exten		57-RCE, XTE, 10E, HSE, LPE	Standard Operating Conditions (unless otherwise specified Operating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended					
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions	
D001	Vdd	Supply Voltage PIC16C5X-RCE PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-LPE	3.25 3.25 4.5 4.5 2.5		6.0 6.0 5.5 5.5 6.0	V V V V		
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode	
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset	
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*		—	V/ms	See Section 5.1 for details on Power-on Reset	
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RCE ⁽³⁾ PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-HSE PIC16C5X-LPE		1.8 1.8 4.8 4.8 9.0 19	3.3 3.3 10 10 20 55	mA mA mA mA μA	Fosc = 4 MHz, VDD = $5.5V$ Fosc = 4 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 16 MHz, VDD = $5.5V$ Fosc = 32 kHz, VDD = $3.25V$, WDT disabled	
D020	IPD	Power-down Current ⁽²⁾	—	5.0 0.8	22 18	μΑ μΑ	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled	

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

- a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
- b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

PIC16LC	PIC16LCR54A-04 PIC16LCR54A-04I (Commercial, Industrial)				$\begin{array}{l} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$					
PIC16CR54A-04, 10, 20 PIC16CR54A-04I, 10I, 20I (Commercial, Industrial)				$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$						
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions			
	Vdd	Supply Voltage								
D001		PIC16LCR54A	2.0		6.25	V				
D001 D001A		PIC16CR54A	2.5 4.5	_	6.25 5.5	V V	RC and XT modes HS mode			
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	_	1.5*	_	V	Device in SLEEP mode			
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset			
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_	—	V/ms	See Section 5.1 for details on Power-on Reset			
	Idd	Supply Current ⁽²⁾								
D005		PICLCR54A	_	10	20 70	μΑ μΑ	Fosc = 32 kHz, VDD = 2.0V Fosc = 32 kHz, VDD = 6.0V			
D005A		PIC16CR54A		2.0 0.8 90	3.6 1.8 350	mA mA μA	RC⁽³⁾ and XT modes: Fosc = 4.0 MHz, VDD = 6.0V Fosc = 4.0 MHz, VDD = 3.0V Fosc = 200 kHz, VDD = 2.5V HS mode:			
				4.8 9.0	10 20	mA mA	Fosc = 10 MHz, VDD = 5.5V Fosc = 20 MHz, VDD = 5.5V			

Legend: Rows with standard voltage device data only are shaded for improved readability.

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

13.2 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

PIC16CR54A-04E, 10E, 20E (Extended)		$\begin{array}{l} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$						
Param No.	Symbol	Characteristic		Min Typ† Max Units		Units	Conditions	
D001	Vdd	Supply Voltage RC, XT and LP modes HS mode	3.25 4.5		6.0 5.5	V V		
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode	
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset	
D004	Svdd	VDD Rise Rate to ensure Power- on Reset	0.05*	_		V/ms	See Section 5.1 for details on Power-on Reset	
D010	IDD	Supply Current ⁽²⁾ RC ⁽³⁾ and XT modes HS mode HS mode		1.8 4.8 9.0	3.3 10 20	mA mA mA	Fosc = 4.0 MHz, Vdd = 5.5V Fosc = 10 MHz, Vdd = 5.5V Fosc = 16 MHz, Vdd = 5.5V	
D020	IPD	Power-down Current ⁽²⁾		5.0 0.8	22 18	μΑ μΑ	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled	

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

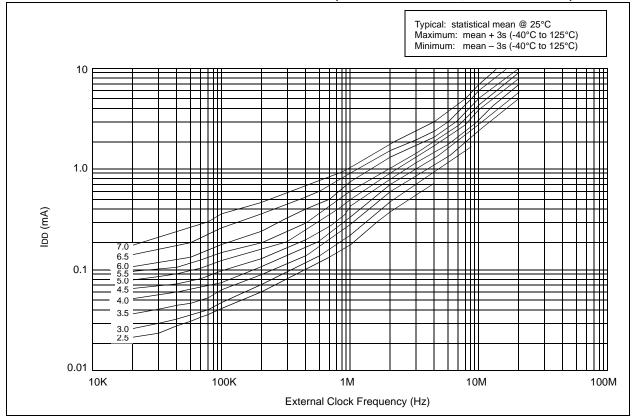














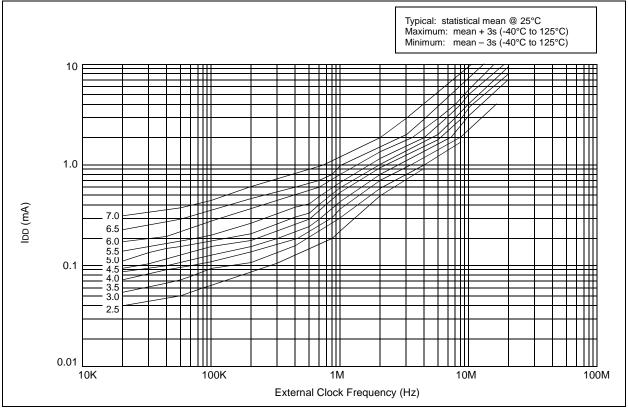


TABLE 14-2: INPUT CAPACITANCE FOR PIC16C54/56

Pin	Typical Capacitance (pF)				
F111	18L PDIP	18L SOIC			
RA port	5.0	4.3			
RB port	5.0	4.3			
MCLR	17.0	17.0			
OSC1	4.0	3.5			
OSC2/CLKOUT	4.3	3.5			
T0CKI	3.2	2.8			

All capacitance values are typical at 25° C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

TABLE 14-3:	INPUT CAPACITANCE FOR
	PIC16C55/57

	Typical Capacitance (pF)				
Pin	28L PDIP (600 mil)	28L SOIC			
RA port	5.2	4.8			
RB port	5.6	4.7			
RC port	5.0	4.1			
MCLR	17.0	17.0			
OSC1	6.6	3.5			
OSC2/CLKOUT	4.6	3.5			
T0CKI	4.5	3.5			

All capacitance values are typical at 25° C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

FIGURE 16-5: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)

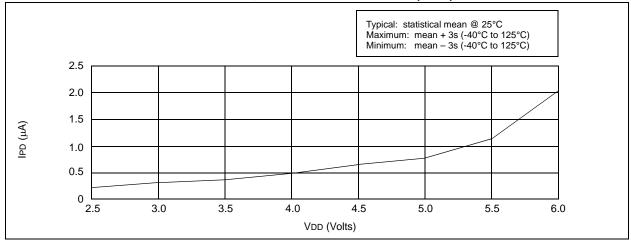






FIGURE 16-18: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD

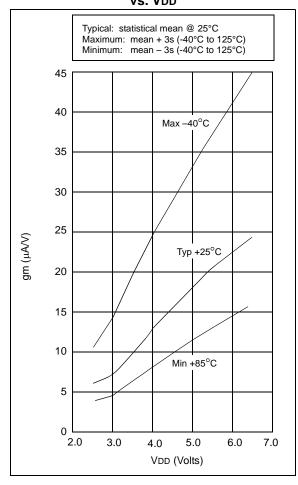
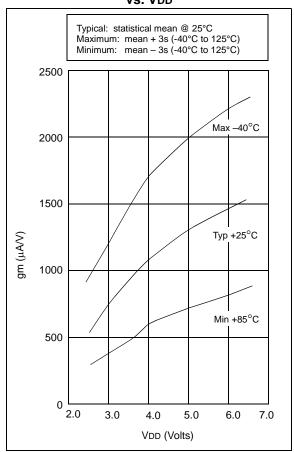
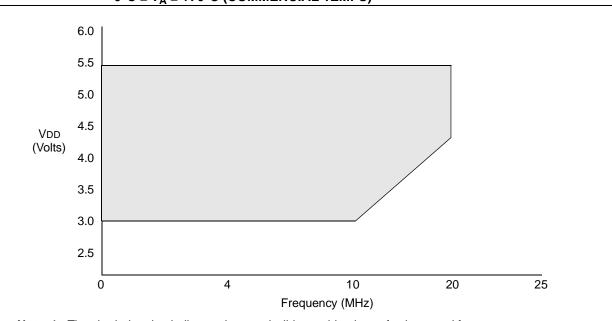


FIGURE 16-19:

TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



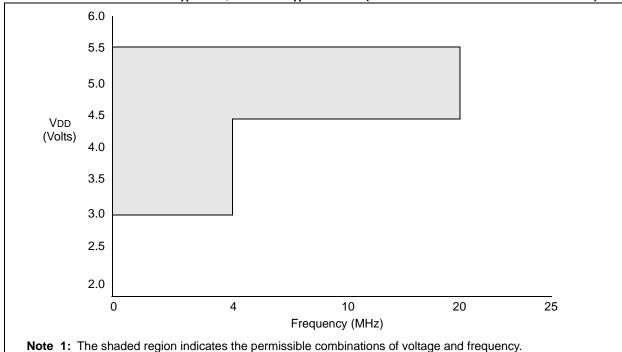






2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.



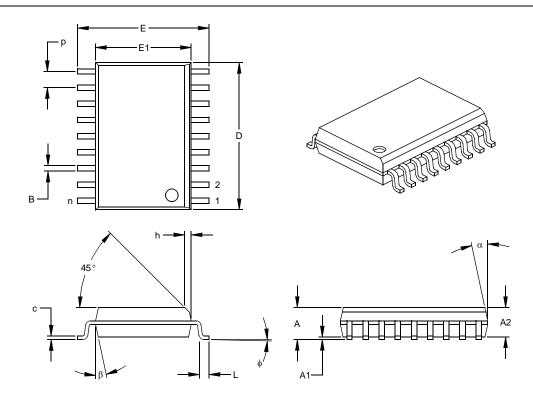


2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency.

Please reference the Product Identification System section for the maximum rated speed of the parts.

18-Lead Plastic Small Outline (SO) - Wide, 300 mil (SOIC)

For the most current package drawings, please see the Microchip Packaging Specification located Note: at http://www.microchip.com/packaging



Units			INCHES*		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	р		.050			1.27	
Overall Height	А	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	С	.009	.011	.012	0.23	0.27	0.30
Lead Width	В	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-013 Drawing No. C04-051

28-Lead Ceramic Dual In-line with Window (JW) - 600 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES*		MILLIMETERS			
Dimensior	MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins			28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.195	.210	.225	4.95	5.33	5.72
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.038	.060	0.38	0.95	1.52
Shoulder to Shoulder Width	Е	.595	.600	.625	15.11	15.24	15.88
Ceramic Pkg. Width	E1	.514	.520	.526	13.06	13.21	13.36
Overall Length	D	1.430	1.460	1.490	36.32	37.08	37.85
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	С	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	В	.016	.020	.023	0.41	0.51	0.58
Overall Row Spacing §	eB	.610	.660	.710	15.49	16.76	18.03
Window Diameter	W	.270	.280	.290	6.86	7.11	7.37

Sontolling Parameter
 Significant Characteristic
 JEDEC Equivalent: MO-103
 Drawing No. C04-013

NOTES:

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